

ABSTRACT OF THE DISCLOSURE

A microelectronic assembly is provided, having redistribution conductors that are formed over a microelectronic die of the assembly instead of through a substrate to which the microelectronic die is mounted. A redistribution conductor is formed by a pair of contacts on the die and a conductive portion connecting the contacts to one another. A wirebonding wire is attached to each contact. One of the wirebonding wires may be used to connect to a terminal on the substrate, a terminal on another die, or to another contact on the same die.